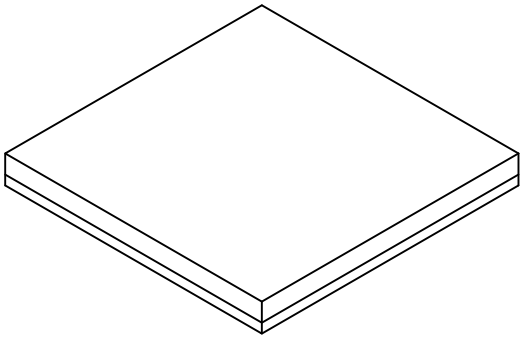
REVISION HISTORY					
REV	DCN NUMBER	DESCRIPTION	ORIGINATOR	INCORPORATOR	DATE
00	C8555	INITIAL RELEASE	ADEBO	SDEFO	3/28/00
01	C10994	ADDED THE 324 BALL MATRIX	SMHAN	SMHAN	12/08/00



7. REFERENCE SPECIFICATIONS:
   A. AAWW SPEC #001-0531-2234: PACKING OPERATION PROCEDURE.
   B. AAWW SPEC #001-0519-2062: MARKING.

6. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.

4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 484.

3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 22 X 22.

2. THE BASIC SOLDER BALL GRID PITCH IS 0.80.

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.

NOTES: UNLESS OTHERWISE SPECIFIED

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS

DECIMAL
X.X ±0.1
X.XX ±0.05
X.XXX ±0.030

ANGULAR ±1°

INTERPRET DIM AND TOL PER ASME Y14.5M - 1994

MATERIAL: N/A

FINISH: N/A

DO NOT SCALE DRAWING

THIRD ANGLE PROJECTION

APPROVALS	DATE
DESIGNED ADEBO	3/21/00
CHECKED DARNO	3/21/00
PRODUCT MANAGER TPANC	3/21/00
RELEASED GSCHU	3/28/00

Amkor Technology, Inc.
Chandler, Arizona, USA
Anam Semiconductor, Inc.,
Seoul, Korea
Amkor Technology Philippines, Inc.
Manila, Philippines

Amkor Technology / ANAM Semiconductor

TITLE: PACKAGE OUTLINE - MAF , 22 X 22 MATRIX, 19.00mm X 19.00mm X 1.40mm, 0.70mm MOLD CAP, 0.46mm BALL, 0.80mm PITCH, LAMINATE SUBSTRATE, AAWW

SIZE	SID NUMBER	DWG NUMBER	REV
A3	N/A	79221	01

STRIP DWG NUMBER/REV	PKG OUTLINE DWG NO.	SCALE	SHEET
N/A	N/A	NONE	1 OF 3

FORM NO: MBFLAM1C1.DWG